

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. - 20. (Canceled)
21. (New) An apparatus comprising:
 - a mounting board having an insulated surface with a plurality of conductive patterns being formed thereon;
 - a hybrid integrated circuit having at least one conductive path and disposed on the mounting board; and
 - an insulating film selectively formed on a surface of the hybrid integrated circuit to insulate the conductive paths from at least some of the conductive patterns.
22. (New) The apparatus of claim 21 wherein the at least one conductive path and conductive patterns in certain locations cross without making contact.
23. (New) The apparatus of claim 21 further comprising at least one semiconductor element coupled to the conductive paths by fine metal wires.

24. (New) The apparatus of claim 23 wherein the at least one of the semiconductor elements, the fine metal wires and the conductive paths are integrally molded as a single package and disposed on the mounting board to couple the conductive path to at least one of the conductive patterns.

25. (New) The apparatus of claim 21 wherein the insulating film comprises a solder resist.

26. (New) The apparatus of claim 21 wherein the mounting board is one of a printed circuit board, a ceramic substrate, a flexible sheet substrate or a metallic substrate.

27. (New) An apparatus comprising:

a mounting board having an insulated surface with a plurality of conductive patterns being formed thereon;

one or more semiconductor devices each having at least one conductive path and disposed on the mounting board; and

an insulating film selectively formed on a surface each of the one or more semiconductor devices to insulate the conductive paths from at least some of the conductive patterns.

28. (New) The apparatus of claim 27 wherein the at least one conductive path and conductive patterns in certain locations cross without making contact.

29. (New) The apparatus of claim 27 further comprising at least one semiconductor element coupled to the conductive paths by fine metal wires.

30. (New) The apparatus of claim 29 wherein the at least one of the semiconductor elements, the fine metal wires and the conductive paths are integrally molded as a single package and disposed on the mounting board to couple the conductive path to at least one of the conductive patterns.

31. (New) The apparatus of claim 27 wherein the insulating film comprises a solder resist.

32. (New) The apparatus of claim 27 wherein the mounting board is one of a printed circuit board, a ceramic substrate, a flexible sheet substrate or a metallic substrate.

33. (New) A method comprising:

forming conductive patterns on a mounting board having an insulated surface;
selectively forming an insulating film on a surface of a hybrid integrated circuit having conductive paths; and
disposing the hybrid integrated on the mounting board,
wherein the insulating film insulates the conductive paths from at least some of the conductive patterns.

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Amendments to the Drawings:

The attached set of formal drawings includes a change to Fig. 20 on sheet 15 from the original drawings submitted in the parent application. Sheet 15 includes Figure 20 only.

In Figure 20, the legend "Prior Art" has been added, as in the parent application.